

Title (en)
SEMICONDUCTOR COMPONENT HANDLING DEVICE HAVING A PERFORMANCE FILM

Title (de)
HALBLEITERKOMPONENTENHANDHABUNGSEINRICHTUNG MIT EINEM PERFORMANCE-FILM

Title (fr)
DISPOSITIF DE MANIPULATION DE COMPOSANTS A SEMI-CONDUCTEURS COMPRENANT UN FILM AMELIORANT LA PERFORMANCE

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Application
EP 02784595 A 20021126

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Abstract (en)
[origin: WO03046950A2] The present invention relates generally to a system and method for including a thin protective containment thermopolymer film, such as PEEK, in the molding process for handlers, transporters, carriers, trays and like devices utilized in the semiconductor processing industry. The thermoplastic film of predetermined size and shape is selectively placed along a shaping surface in a mold cavity for alignment with a desired target surface of a moldable material. The molding process causes a surface of the film to bond to a contact surface of the moldable material such that the film is permanently adhered to the moldable material. As a result, a compatible polymer film can be selectively bonded only to those target surfaces where performance characteristics such as abrasion resistance, heat resistance, chemical resistance, outgassing containment, rigidity enhancement, hardness, creep reduction, fluid absorption containment, and the like is needed.

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Citation (search report)
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• [DX] DE 19924182 A1 19991202 - FLUOROWARE INC [US]
• [E] WO 03046952 A2 20030605 - ENTEGRIS INC [US], et al & US 6428729 B1 20020806 - BHATT SANJIV M [US], et al
• See references of WO 03046950A2

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